

**APPLICATION DATA SHEET**

Electronic Version v14

Stylesheet Version v14.0

**Title of Invention**

Micromachined Capacitive RF Pressure Sensor

Application Type : regular, utility

**Request Not To Publish**

I/We hereby request that the attached application not be published under 37 U.S.C. 122(b).

I/We hereby certify that the invention disclosed in the attached application has not and will not be the subject of an application filed in another country, or under a multilateral agreement, that requires publication at eighteen months after filing.

Correspondence address:

Customer Number: 038167



## Inventor Information:

Inventor 1:

**Applicant Authority Type:** Inventor  
**Citizenship:** CN  
**Name prefix:** Dr.  
**Given Name:** Yunlong  
**Family Name:** Wang  
**Residence:**  
**City of Residence:** Fremont  
**State of Residence:** CA  
**Country of Residence:** US  
**Address-1 of Mailing Address:** 47667 Gridley Court  
**Address-2 of Mailing Address:**  
**City of Mailing Address:** Fremont  
**State of Mailing Address:** CA  
**Postal Code of Mailing Address:** 94539  
**Country of Mailing Address:** US  
**Phone:**  
**Fax:**  
**E-mail:** mark.wang@gmems.com

Attorney Information:

practitioner(s) at Customer Number:

038167



as my attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.

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Assignee 1:

<b>Organization Name:</b>	General MEMS Corporation
<b>Address-1 of Mailing Address:</b>	47667 Gridley Court
<b>Address-2 of Mailing Address:</b>	
<b>City of Mailing Address:</b>	Fremont
<b>State of Mailing Address:</b>	CA
<b>Postal Code of Mailing Address:</b>	94539
<b>Country of Mailing Address:</b>	US
<b>Phone:</b>	(510)364-7930
<b>Fax:</b>	(510)651-1559
<b>E-mail:</b>	mark.wang@gmems.com